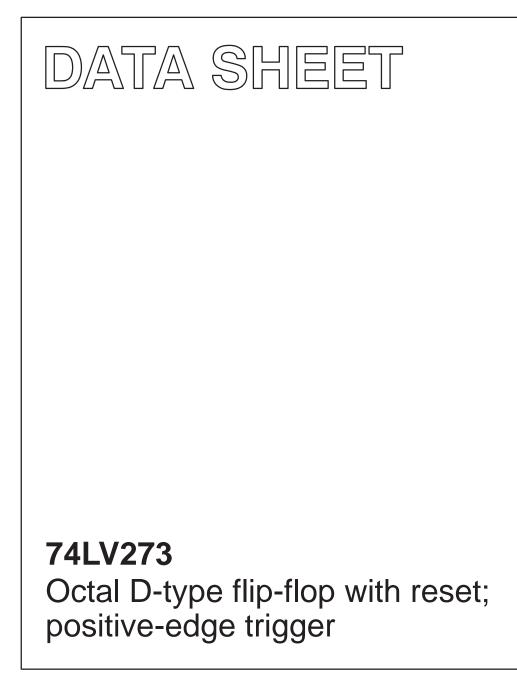
INTEGRATED CIRCUITS



Product specification Supersedes data of 1997 Apr 07 IC24 Data Handbook

1998 May 29



74LV273

FEATURES

- Wide operating voltage: 1.0 to 5.5V
- Optimized for Low Voltage applications: 1.0 to 3.6V
- Accepts TTL input levels between V_{CC} = 2.7V and V_{CC} = 3.6V
- Typical V_{OLP} (output ground bounce) < 0.8V @ V_{CC} = 3.3V, $T_{amb} = 25^{\circ}C$
- Typical V_{OHV} (output V_{OH} undershoot) $> 2V @ V_{CC} = 3.3V$, T_{amb} = 25°C
- Ideal buffer for MOS microprocessor or memory
- Common clock and master reset
- Output capability: standard
- I_{CC} category: MSI

QUICK REFERENCE DATA

$2E^{\circ}C + - + < 2E^{\circ}C$

DESCRIPTION

The 74LV273 is a low-voltage Si-gate CMOS device and is pin and function compatible with the 74HC/HCT273.

The 74LV273 has eight edge-triggered , D-type flip-flops with individual D inputs and Q outputs. The common clock (CP) and master reset (MR) inputs load and reset (clear) all flip-flops simultaneously. The state of each D input, one set-up time before the LOW-to-HIGH clock transition, is transferred to the corresponding output (Qn) of the flip-flop.

All outputs will be forced LOW independently of clock or data inputs by a LOW voltage level on the \overline{MR} input.

The device is useful for applications where the true output only is required and the clock and master reset are common to all storage elements.

SYMBOL	PARAMETER	CONDITIONS	TYPICAL	UNIT
t _{PHL} /t _{PLH}	$\begin{array}{c} \mbox{Propagation delay} \\ \mbox{CP to } \mbox{Q}_{n;} \\ \mbox{MR to } \mbox{Q}_{n} \end{array}$	C _L = 15pF V _{CC} = 3.3V	12 13	ns
f _{max}	Maximum clock frequency		110	MHz
Cl	Input capacitance		3.5	pF
C _{PD}	Power dissipation capacitance per flip-flop	Notes 1 and 2	20	pF

NOTES:

 C_{PD} is used to determine the dynamic power dissipation (P_D in μW) 1. $\begin{array}{l} \mathsf{P}_{D} = \mathsf{C}_{PD} \times \mathsf{V}_{CC}^2 \times \mathsf{f}_i + \Sigma \left(\mathsf{C}_L \times \mathsf{V}_{CC}^2 \times \mathsf{f}_o\right) \text{ where:} \\ \mathsf{f}_i = \mathsf{input} \text{ frequency in MHz; } \mathsf{C}_L = \mathsf{output} \text{ load capacitance in pF;} \\ \mathsf{f}_o = \mathsf{output} \text{ frequency in MHz; } \mathsf{V}_{CC} = \mathsf{supply voltage in V;} \\ \Sigma \left(\mathsf{C}_L \times \mathsf{V}_{CC}^2 \times \mathsf{f}_o\right) = \mathsf{sum of the outputs.} \end{array}$

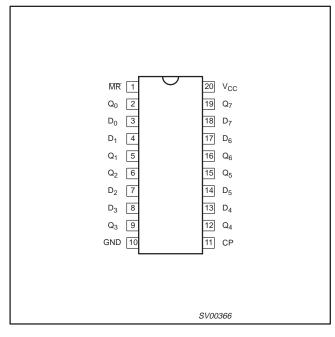
2. The condition is $V_I = GND$ to V_{CC}

ORDERING INFORMATION

PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	PKG. DWG. #
20-Pin Plastic DIL	–40°C to +125°C	74LV273 N	74LV273 N	SOT146-1
20-Pin Plastic SO	–40°C to +125°C	74LV273 D	74LV273 D	SOT163-1
20-Pin Plastic SSOP Type II	–40°C to +125°C	74LV273 DB	74LV273 DB	SOT339-1
20-Pin Plastic TSSOP	–40°C to +125°C	74LV273 PW	74LV273PW DH	SOT360-1

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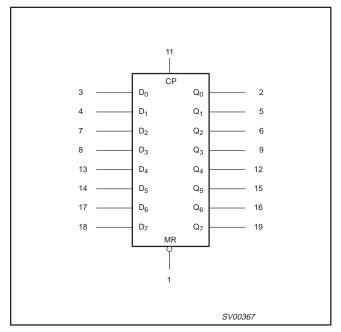
PIN CONFIGURATION



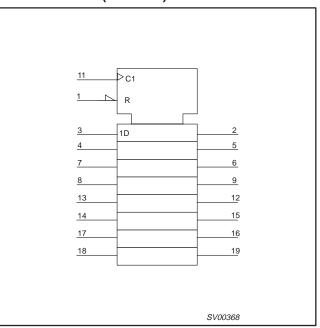
PIN DESCRIPTION

PIN NUMBER	SYMBOL	FUNCTION
1	MR	Master reset input (active-LOW)
2, 5, 6, 9, 12, 15, 16, 19	Q_0 to Q_7	Flip-flop outputs
3, 4, 7, 8, 13, 14, 17, 18	D ₀ to D ₇	Data inputs
10	GND	Ground (0V)
11	СР	Clock input (LOW-to-HIGH, edge- triggered)
20	V _{CC}	Positive supply voltage

LOGIC SYMBOL

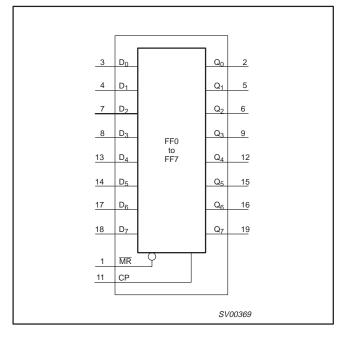


LOGIC SYMBOL (IEEE/IEC)



74LV273

FUNCTIONAL DIAGRAM



RECOMMENDED OPERATING CONDITIONS

FUNCTION TABLE

OPERATING MODES		INPUTS	OUTPUTS		
OPERATING MODES	MR	СР	D _n	Q ₀ to Q ₇	
Reset (clear)	L	Х	Х	L	
Load ('1')	Н	↑	h	Н	
Load ('0')	Н	\uparrow	Ι	L	

Н = HIGH voltage level

 HIGH voltage level one set-up time prior to the LOW-to-HIGH CP transition h

LOW voltage level =

L LOW voltage level one set-up time prior to the LOW-to-HIGH CP transition L

= LOW-to-HIGH clock transition

 \uparrow Х = Don't care

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP.	MAX	UNIT
V _{CC}	DC supply voltage	See Note1	1.0	3.3	5.5	V
VI	Input voltage		0	-	V _{CC}	V
Vo	Output voltage		0	-	V _{CC}	V
T _{amb}	Operating ambient temperature range in free air	See DC and AC characteristics	-40 -40		+85 +125	°C
t _r , t _f	Input rise and fall times	$\begin{array}{l} V_{CC} = 1.0V \mbox{ to } 2.0V \\ V_{CC} = 2.0V \mbox{ to } 2.7V \\ V_{CC} = 2.7V \mbox{ to } 3.6V \\ V_{CC} = 3.6V \mbox{ to } 5.5V \end{array}$			500 200 100 50	ns/V

NOTES:

1. The LV is guaranteed to function down to V_{CC} = 1.0V (input levels GND or V_{CC}); DC characteristics are guaranteed from V_{CC} = 1.2V to V_{CC} = 5.5V.

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ABSOLUTE MAXIMUM RATINGS^{1, 2}

In accordance with the Absolute Maximum Rating System (IEC 134)

Voltages are referenced to GND (ground = 0V)

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V _{CC}	DC supply voltage		-0.5 to +7.0	V
±I _{IK}	DC input diode current	$V_{\rm I} < -0.5 \text{ or } V_{\rm I} > V_{\rm CC} + 0.5 V$	20	mA
±ΙΟΚ	DC output diode current	$V_{O} < -0.5$ or $V_{O} > V_{CC} + 0.5V$	50	mA
±lο	DC output source or sink current – standard outputs	$-0.5V < V_{O} < V_{CC} + 0.5V$	25	mA
±I _{GND} , ±I _{CC}	DC V _{CC} or GND current for types with -standard outputs		50	mA
T _{stg}	Storage temperature range		–65 to +150	°C
P _{TOT}	Power dissipation per package –plastic DIL –plastic mini-pack (SO) –plastic shrink mini-pack (SSOP and TSSOP)	for temperature range: -40 to +125°C above +70°C derate linearly with 12mW/K above +70°C derate linearly with 8 mW/K above +60°C derate linearly with 5.5 mW/K	750 500 400	mW

NOTES:

 Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

2. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

DC CHARACTERISTICS FOR THE LV FAMILY

Over recommended operating conditions voltages are referenced to GND (ground = 0V)

					LIMITS			
SYMBOL	PARAMETER	TEST CONDITIONS	-40)°C to +8	5°C	-40°C to	o +125°C	UNIT
			MIN	TYP ¹	MAX	MIN	MAX	
		$V_{CC} = 1.2V$	0.9			0.9		
VIH	HIGH level Input	$V_{CC} = 2.0V$	1.4			1.4		v
VIH	voltage	V _{CC} = 2.7 to 3.6V	2.0			2.0		Ň
		V _{CC} = 4.5 to 5.5V	0.7*V _{CC}			0.7*V _{CC}		1
		$V_{CC} = 1.2V$			0.3		0.3	
VIL	LOW level Input	$V_{CC} = 2.0 V$			0.6		0.6	
VIL	voltage	V _{CC} = 2.7 to 3.6V			0.8		0.8	Ň
		V _{CC} = 4.5 to 5.5			0.3*V _{CC}		0.3*V _{CC}	
		$V_{CC} = 1.2V; V_I = V_{IH} \text{ or } V_{IL;} - I_O = 100 \mu A$		1.2				
		$V_{CC} = 2.0V; V_I = V_{IH} \text{ or } V_{IL;} - I_O = 100 \mu A$	1.8	2.0		1.8		
	HIGH level output voltage; all outputs	$V_{CC} = 2.7V; V_I = V_{IH} \text{ or } V_{IL;} - I_O = 100 \mu A$	2.5	2.7		2.5		V
.,		$V_{CC} = 3.0V; V_I = V_{IH} \text{ or } V_{IL;} - I_O = 100 \mu A$	2.8	3.0		2.8		
V _{ОН}		$V_{CC} = 4.5V; V_I = V_{IH} \text{ or } V_{IL;} - I_O = 100 \mu A$	4.3	4.5		4.3		1
	HIGH level output voltage;	$V_{CC} = 3.0V; V_I = V_{IH} \text{ or } V_{IL;} -I_O = 6mA$	2.40	2.82		2.20		v
	STANDARD outputs	$V_{CC} = 4.5 V; V_I = V_{IH} \text{ or } V_{IL;} -I_O = 12 \text{mA}$	3.60	4.20		3.50		ľ
		V_{CC} = 1.2V; V_I = V_{IH} or V_{IL} ; I_O = 100 μ A		0				
		V_{CC} = 2.0V; V_I = V_{IH} or V_{IL} ; I_O = 100 μ A		0	0.2		0.2	
	LOW level output voltage; all outputs	V_{CC} = 2.7V; V_I = V_{IH} or V_{IL} ; I_O = 100 μ A		0	0.2		0.2	V
		$V_{CC} = 3.0V; V_I = V_{IH} \text{ or } V_{IL;} I_O = 100 \mu A$		0	0.2		0.2	
V _{OL}		V_{CC} = 4.5V; V_I = V_{IH} or V_{IL} ; I_O = 100 μ A		0	0.2		0.2	
	LOW level output voltage;	$V_{CC} = 3.0V; V_I = V_{IH} \text{ or } V_{IL;} I_O = 6mA$		0.25	0.40		0.50	
	STANDARD outputs	V_{CC} = 4.5V;V_I = V_{IH} \text{ or } V_{IL;} I_O = 12mA		0.35	0.55		0.65	

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DC CHARACTERISTICS FOR THE LV FAMILY (Continued)

Over recommended operating conditions voltages are referenced to GND (ground = 0V)

SYMBOL	PARAMETER	TEST CONDITIONS	LIMITS					
STMBOL	FARAMETER	TEST CONDITIONS	-40°C to +85°C			-40°C to	UNIT	
lı	Input leakage current	V_{CC} = 5.5V; V_{I} = V_{CC} or GND			1.0		1.0	μΑ
Icc	Quiescent supply current; MSI	$V_{CC} = 5.5V; V_I = V_{CC} \text{ or GND}; I_O = 0$			20.0		160	μΑ
ΔI _{CC}	Additional quiescent supply current per input	$V_{CC} = 2.7V$ to 3.6V; $V_{I} = V_{CC} - 0.6V$			500		850	μΑ

NOTE:

1. All typical values are measured at $T_{amb} = 25^{\circ}C$.

AC CHARACTERISTICS

 $\text{GND}=\text{0V};\, t_{\text{r}}=t_{\text{f}}=\text{2.5ns};\, \text{C}_{\text{L}}=\text{50pF};\, \text{R}_{\text{L}}=\text{1K}\Omega$

SYMBOL	PARAMETER	WAVEFORM	CONDITION		LIMITS 40 to +85 °	°C		IITS +125 ℃	UNIT	
			V _{CC} (V)	MIN	TYP ¹	MAX	MIN	MAX		
			1.2	-	75	-	-	-		
			2.0	-	26	32	-	41		
t _{PHL} /t _{PLH}	Propagation delay CP to Q _n	Figure 1	2.7	-	19	24	-	30	ns	
			3.0 to 3.6	-	14 ²	19	-	24		
			4.5 to 5.5	-	-	16	-	20		
			1.2	-	80	-	-	-		
t _{PHL} Propagation delay MR to Q _n		2.0	-	27	44	-	56			
	Figure 2	2.7	-	20	33	-	41	ns		
		3.0 to 3.6	-	15 ²	26	-	33			
		4.5 to 5.5	-	-	22	-	28			
			2.0	34	9	-	41	-		
t _W Clock pulse width HIGH or LOW	Figure 1	2.7	25	6	-	30	-	ns		
			3.0 to 3.6	20	5 ²	-	24	-		
			2.0	34	10	-	41	-	ns	
t _W	Master reset pulse width LOW	Figure 2	2.7	25	8	-	30	-		
			3.0 to 3.6	20	6 ²	-	24	-		
			1.2	-	-10	-	-	-	ns	
+	Removal time	Figure 2	2.0	5	-4	-	5	-		
t _{rem}	MR to CP	Figure 2	2.7	5	-3	-	5	-		
			3.0 to 3.6	5	-2 ²	-	5	-		
			1.2	-	20	-	-	-		
+	Set-up time	Figure 3	2.0	22	7	-	26	-	ns	
t _{su}	D _n to CP		2.7	16	5	-	19	-	115	
			3.0 to 3.6	13	4 ²	-	15	-		
			1.2	-	-10	-	-	-		
	Hold time	Eiguro 2	2.0	5	-4	-	5	-	20	
t _h	D _n to CP	Figure 3	2.7	5	-3	-	5	-	ns	
			3.0 to 3.6	5	-2 ²	-	5	-		
			2.0	14	40	-	12	-		
f _{max}	Maximum clock pulse frequency	Figure 1	2.7	19	75	-	16	-	MHz	
			3.0 to 3.6	24	100 ²	-	20	-		

NOTE:

1. Unless otherwise stated, all typical values are at $T_{amb} = 25^{\circ}C$.

2. Typical value measured at V_{CC} = 3.3V.

3. Typical value measured at V_{CC} = 5.0V.

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AC WAVEFORMS

 V_M = 1.5V at $V_{CC} \ge 2.7V \le 3.6V$ V_M = 0.5V * V_{CC} at $V_{CC} < 2.7V$ and $\ge 4.5V$ V_{OL} and V_{OH} are the typical output voltage drop that occur with the output load.

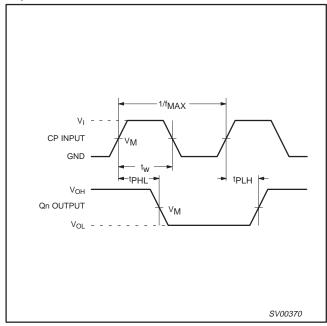


Figure 1. The clock (CP) to output (Q_n) propagation delays, the clock pulse width and the maximum clock pulse frequency

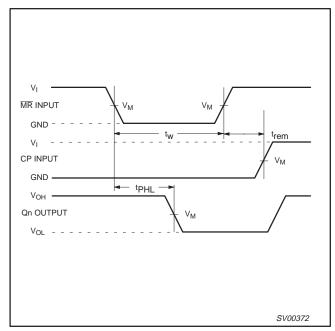


Figure 2. The master reset (\overline{MR}) pulse width, the master reset to output (Q_n) propagations delay and the master reset to clock (CP) removal time

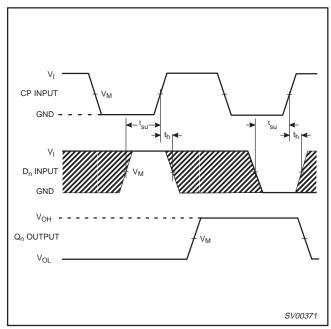


Figure 3. Data set-up and hold times for the data input (D_n)

NOTE:

The shaded areas indicate when the input is permitted to change for predictable output performance.

TEST CIRCUIT

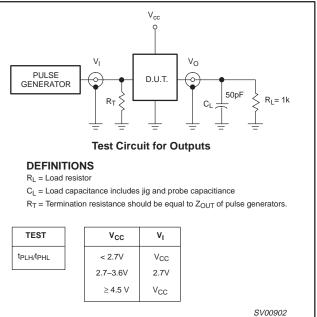
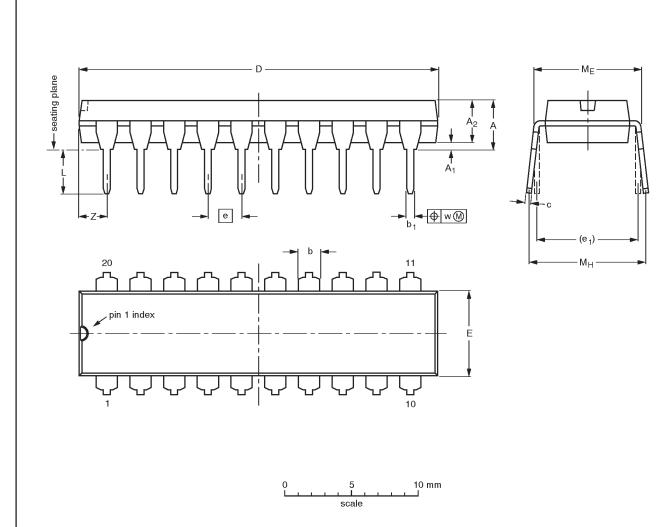


Figure 4. Load circuitry for switching times

DIP20: plastic dual in-line package; 20 leads (300 mil)



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	c	р ⁽¹⁾	E ⁽¹⁾	e	e ₁	L	ME	M _H	w	Z ⁽¹⁾ max.
mm	4.2	0.51	3.2	1.73 1.30	0.53 0.38	0.36 0.23	26.92 26.54	6.40 6.22	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2.0
inches	0.17	0.020	0.13	0.068 0.051	0.021 0.015	0.014 0.009	1.060 1.045	0.25 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.078

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

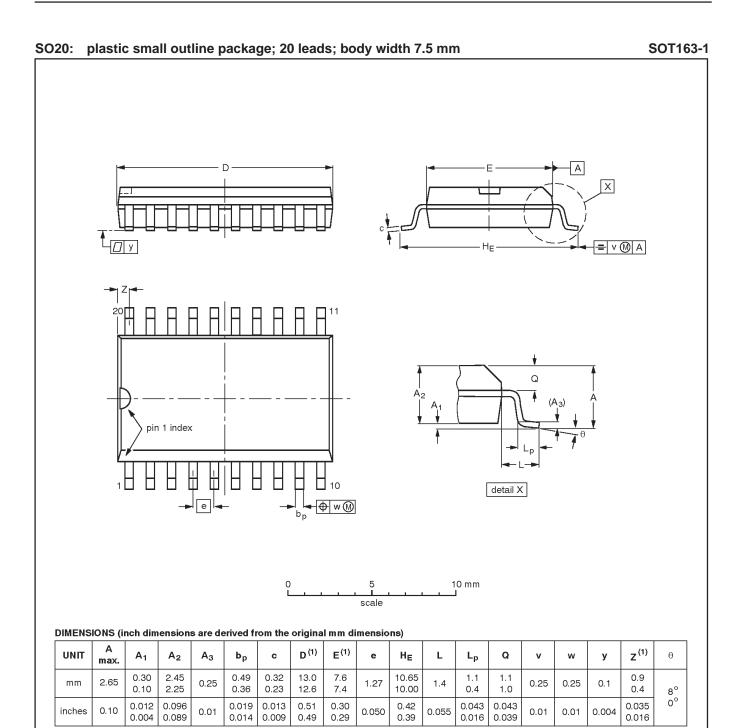
OUTLINE		REFERENCES EUROF					
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE	
SOT146-1			SC603			-92-11-17 95-05-24	

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Product specification

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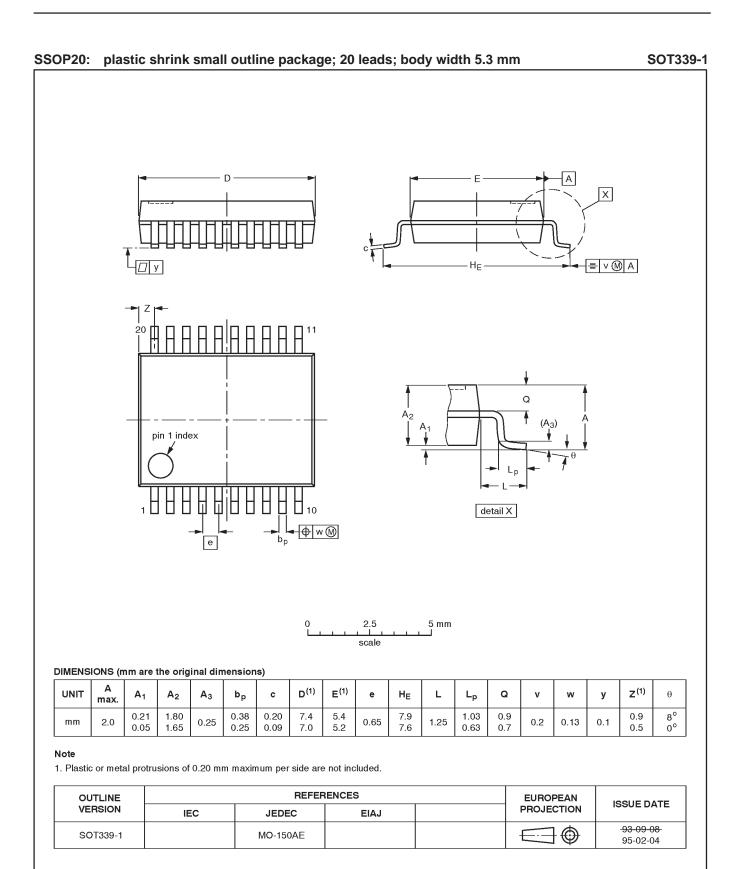


Note

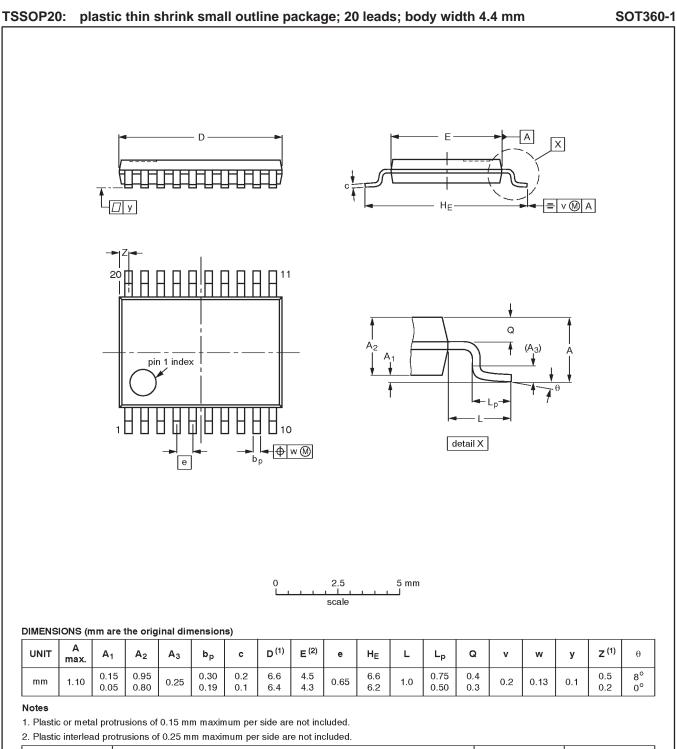
1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE		REFER	ENCES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE
SOT163-1	075E04	MS-013AC			-92-11-17 95-01-24

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OUTLINE VERSION	REFERENCES				EUROPEAN	ISSUE DATE
	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT360-1		MO-153AC				-93-06-16- 95-02-04

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DEFINITIONS						
Data Sheet Identification	Product Status	Definition				
Objective Specification	Formative or in Design	This data sheet contains the design target or goal specifications for product development. Specifications may change in any manner without notice.				
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